Hot Mounting Wax, Clear Stick

Date: 10/2020, v1.1

Refer to the SDS document for additional safety information.

GHS07 GHS05 GHS08

Technical Information	
Melting Temperature	50 °C (122 °F)
Flow Point	75 °C (167 °F)
Ignition Point	580 °C (1,076 °F)
Viscosity	25,000 cP @ 75 °C 5,000 cP @ 100 °C 2,000 cP @ 125 °C

Clear mounting wax (#71-10040) provides a quick and strong bond between samples and fixtures for cutting and/or polishing. While mounting wax can be used with samples of any size, it is easier to achieve a uniform wax thickness when preparing smaller samples (≤10 mm^2).

It is typically used for dicing, mounting cross-sections for SEM/TEM analysis and lapping and polishing optical, ceramic and semiconductor components.

Acetone can be used to dissolve/remove the wax after use, as well as to thin the wax for improved sample registration. The wax is non-soluble in water.

Instructions

1. Heat a fixture on a hot plate at 150 ºC.
2. Place a small amount of mounting wax on the surface of the fixture.
3. Once the wax is soft, place the sample on the fixture.

   Note: For an ultra-thin layer, dip a cotton-tipped applicator in acetone and run it along the wax layer until the wax appears hazy and has no clumps.
4. Remove the fixture from the hot plate and allow it to cool at room temperature.
5. To remove the sample after preparation, place the fixture back on the hot plate and reheat the wax. Once the wax is soft, remove the sample; the wax can be reused.

   Note: Do not quench the fixture to cool the wax; the wax may become brittle, causing the sample to break off. For some samples, a mount leveling press (#120-30020) can be used to even out and thin the wax layer, improving registration between the sample and fixture.